

9. Reliable Integrated Thermal Packaging for Power Electronics

Course Leader: Patrick McCuskey – University of Maryland

Course Objective:

Power electronics are becoming ubiquitous in engineered systems as they replace traditional ways to control the generation, distribution, and use of energy. They are used in products as diverse as home appliances, cell phone towers, aircraft, wind turbines, radar systems, smart grids, and data centers. This widespread incorporation has resulted in significant improvements in efficiency over previous technologies, but it also has made it essential that the reliability of power electronics be characterized and enhanced. Recently, increased power levels, made possible by new compound semiconductor materials, combined with increased packaging density have led to higher heat densities in power electronic systems, especially inside the switching module, making thermal management more critical to performance and reliability of power electronics.

This course will emphasize approaches to integrated thermal packaging that address performance limits and reliability concerns associated with increased power levels and power density. Following a quick review of active heat transfer techniques, along with prognostic health management, this short course will present the latest developments in the materials (e.g. organic, flexible), packaging, assembly, and thermal management of power electronic modules, MEMS, and systems and in the techniques for their reliability assessment.

Course Outline:

1. Motivation for Integrated Thermal Packaging for Reliable Power Electronic Systems and Heterogeneous Integration
2. Simulation and Assessment of Active Thermal Management Techniques: Air; Single Phase Liquid; Two Phase; Heat Pipes; and, Thermoelectric
3. Application of Thermal Management Techniques to Commercial Power Systems
4. Durability Assessment: Failure Modeling; Simulation; Testing; and, Health Monitoring
5. Reliability and Thermal Packaging of Active Devices: Si; SiC; GaN; and, Interconnects
6. Reliability and Thermal Packaging of Switching Modules, including organic encapsulants
7. Reliability in Rigid Assembly Packaging: PCBs; Solders; and, Passives
8. Flexible Materials, Packaging, and Thermal Management: Flex circuit and OLED
9. Reliability of Additive Manufactured and Embedded Power Electronics

Who Should Attend:

This course is intended for engineers and managers who want to learn more about the thermal limitations and reliability concerns involved in the heterogeneous integration and packaging of power electronic devices and systems.

Bio:

Dr. Patrick McCluskey (Ph.D., Materials Science and Engineering, Lehigh University) is a Professor of Mechanical Engineering at the University of Maryland, College Park, where he conducts research in the areas of thermal management, reliability, and packaging of electronic microsystems for use in extreme temperature environments and high-power applications. Dr. McCluskey has published more than 150 refereed technical articles on these subjects, and has edited three books. He has also served as technical chairman for IEEE and IMAPS international conferences and workshops on high temperature electronics, low temperature electronics, and power electronic packaging. Dr. McCluskey has provided short courses on extreme temperature electronics and power electronics for companies in the aerospace,

automotive, motor drives, energy exploration and generation, and defense industries. He is an associate editor of the IEEE Transactions on Components, Packaging, and Manufacturing Technology, a fellow of IMAPS, a senior member of IEEE, a member of the Board of Governors of IEEE EPS, and a member of ASME.